

OL-PCF8576CU

Wire bond die; 56 bonding pads

10 February 2016

Package information

1. Package summary

Terminal position code	U (upper)
Package type descriptive code	UC
Package type industry code	UC
Package style descriptive code	UC (uncased chip)
Package style suffix code	NA (not applicable)
Package body material type	X (other)
IEC package outline code	---
JEDEC package outline code	---
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	26-10-2011

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	-	-	2.82	-	mm
E	package width	-	-	3	-	mm
A	seated height	-	-	0.38	-	mm
n ₂	actual quantity of termination	-	-	56	-	



2. Package outline

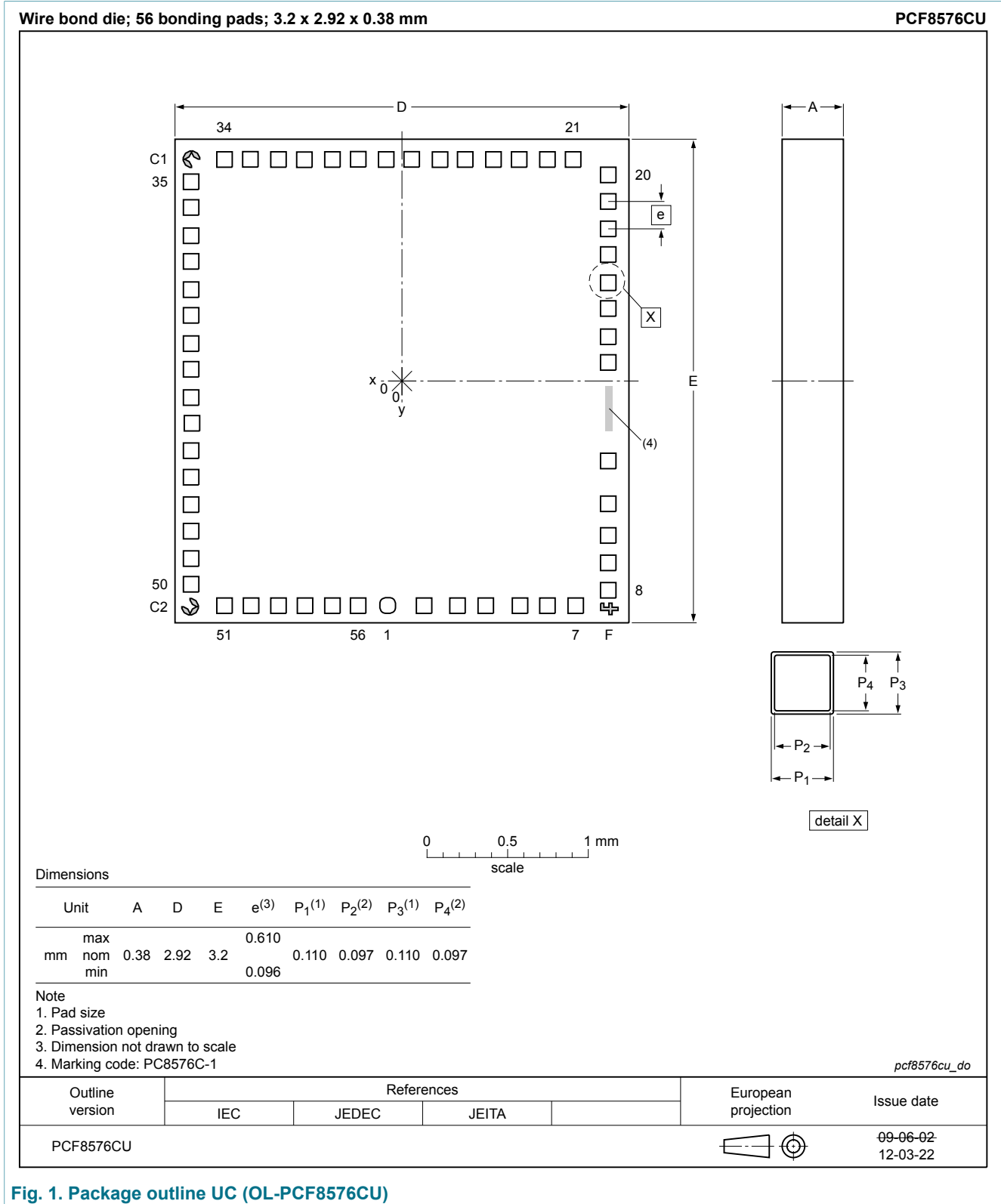


Fig. 1. Package outline UC (OL-PCF8576CU)

3. Legal information

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